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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	MPC8xx
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	66MHz
Co-Processors/DSP	Communications; CPM
RAM Controllers	DRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	10Mbps (1), 10/100Mbps (1)
SATA	-
USB	-
Voltage - I/O	3.3V
Operating Temperature	-40°C ~ 100°C (TA)
Security Features	-
Package / Case	357-BBGA
Supplier Device Package	357-PBGA (25x25)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/kmpc859dslczp66a

- Interrupts
  - Seven external interrupt request (IRQ) lines
  - Twelve port pins with interrupt capability
  - The MPC866P and MPC866T have 23 internal interrupt sources; the MPC859P, MPC859T, and MPC859DSL have 20 internal interrupt sources.
  - Programmable priority between SCCs (MPC866P and MPC866T)
  - Programmable highest priority request
- Communications processor module (CPM)
  - RISC controller
  - Communication-specific commands (for example, GRACEFUL STOP TRANSMIT, ENTER HUNT MODE, and RESTART TRANSMIT)
  - Supports continuous mode transmission and reception on all serial channels
  - Up to 8-Kbytes of dual-port RAM
  - MPC866P and MPC866T have 16 serial DMA (SDMA) channels; MPC859P, MPC859T, and MPC859DSL have 10 serial DMA (SDMA) channels.
  - Three parallel I/O registers with open-drain capability
- Four baud rate generators
  - Independent (can be connected to any SCC or SMC)
  - Allow changes during operation
  - Autobaud support option
- MPC866P and MPC866T have four SCCs (serial communication controller); MPC859P, MPC859T, and MPC859DSL have one SCC; and SCC1 on MPC859DSL supports Ethernet only.
  - Serial ATM capability on all SCCs
  - Optional UTOPIA port on SCC4
  - Ethernet/IEEE 802.3 optional on SCC1–4, supporting full 10-Mbps operation
  - HDLC/SDLC
  - HDLC bus (implements an HDLC-based local area network (LAN))
  - Asynchronous HDLC to support PPP (point-to-point protocol)
  - AppleTalk
  - Universal asynchronous receiver transmitter (UART)
  - Synchronous UART
  - Serial infrared (IrDA)
  - Binary synchronous communication (BISYNC)
  - Totally transparent (bit streams)
  - Totally transparent (frame based with optional cyclic redundancy check (CRC)
- Two SMCs (serial management channels) (MPC859DSL has one SMC (SMC1) for UART.)
  - UART
  - Transparent
  - General circuit interface (GCI) controller
  - Can be connected to the time-division multiplexed (TDM) channels

3 Maximum Tolerated Ratings

This section provides the maximum tolerated voltage and temperature ranges for the MPC866/859. Table 2 shows the maximum tolerated ratings, and Table 3 shows the operating temperatures.

Table 2. Maximum Tolerated Ratings

Rating	Symbol	Value	Unit
Supply voltage [1]	VDDH	– 0.3 to 4.0	V
	VDDL	– 0.3 to 2.0	V
	VDDSYN	– 0.3 to 2.0	V
	Difference between VDDL to VDDSYN	100	mV
Input voltage [2]	V_{in}	GND – 0.3 to VDDH	V
Storage temperature range	T_{stg}	–55 to +150	°C

[1] The power supply of the device must start its ramp from 0.0 V.

[2] Functional operating conditions are provided with the DC electrical specifications in Table 6. Absolute maximum ratings are stress ratings only; functional operation at the maxima is not guaranteed. Stress beyond those listed may affect device reliability or cause permanent damage to the device. See page 15.
Caution: All inputs that tolerate 5 V cannot be more than 2.5 V greater than VDDH. This restriction applies to power-up and normal operation (that is, if the MPC866/859 is unpowered, a voltage greater than 2.5 V must not be applied to its inputs).

Table 3. Operating Temperatures

Rating	Symbol	Value	Unit
Temperature [1] (standard)	$T_{A(min)}$	0	°C
	$T_{j(max)}$	95	°C
Temperature (extended)	$T_{A(min)}$	–40	°C
	$T_{j(max)}$	100	°C

[1] Minimum temperatures are guaranteed as ambient temperature, T_A. Maximum temperatures are guaranteed as junction temperature, T_j.

This device contains circuitry protecting against damage due to high-static voltage or electrical fields; however, it is advised that normal precautions be taken to avoid application of any voltages higher than maximum-rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate logic voltage level (for example, either GND or V_{DD}).

5 Power Dissipation

Table 5 shows power dissipation information. The modes are 1:1, where CPU and bus speeds are equal, and 2:1 mode, where CPU frequency is twice the bus speed.

Table 5. Power Dissipation (P_D)

Die Revision	Bus Mode	CPU Frequency	Typical [1]	Maximum [2]	Unit
0	1:1	50 MHz	110	140	mW
		66 MHz	150	180	mW
	2:1	66 MHz	140	160	mW
		80 MHz	170	200	mW
		100 MHz	210	250	mW
		133 MHz	260	320	mW

[1] Typical power dissipation at VDDL and VDDSYN is at 1.8 V. and VDDH is at 3.3 V.

[2] Maximum power dissipation at VDDL and VDDSYN is at 1.9 V, and VDDH is at 3.465 V.

NOTE

Values in Table 5 represent VDDL based power dissipation and do not include I/O power dissipation over VDDH. I/O power dissipation varies widely by application due to buffer current, depending on external circuitry. The VDDSYN power dissipation is negligible.

6 DC Characteristics

Table 6 shows the DC electrical characteristics for the MPC866/859.

Table 6. DC Electrical Specifications

Characteristic	Symbol	Min	Max	Unit
Operating voltage	VDDL (core)	1.7	1.9	V
	VDDH (I/O)	3.135	3.465	V
	VDDSYN [1]	1.7	1.9	V
	Difference between VDDL to VDDSYN	—	100	mV
Input high voltage (all inputs except EXTAL and EXTCLK) [2]	VIH	2.0	3.465	V

7.5 Experimental Determination

To determine the junction temperature of the device in the application after prototypes are available, the thermal characterization parameter (Ψ_{JT}) can be used to determine the junction temperature with a measurement of the temperature at the top center of the package case using the following equation:

$$T_J = T_T + (\Psi_{JT} \times P_D)$$

where:

Ψ_{JT} = thermal characterization parameter

T_T = thermocouple temperature on top of package

P_D = power dissipation in package

The thermal characterization parameter is measured per JESD51-2 specification published by JEDEC using a 40 gauge type T thermocouple epoxied to the top center of the package case. The thermocouple should be positioned so that the thermocouple junction rests on the package. A small amount of epoxy is placed over the thermocouple junction and over about 1 mm of wire extending from the junction. The thermocouple wire is placed flat against the package case to avoid measurement errors caused by cooling effects of the thermocouple wire.

7.6 References

Semiconductor Equipment and Materials International(415) 964-5111
805 East Middlefield Rd.
Mountain View, CA 94043

MIL-SPEC and EIA/JESD (JEDEC) specifications800-854-7179 or
(Available from Global Engineering Documents)303-397-7956

JEDEC Specifications http://www.jedec.org

1. C.E. Triplett and B. Joiner, “An Experimental Characterization of a 272 PBGA Within an Automotive Engine Controller Module,” Proceedings of SemiTherm, San Diego, 1998, pp. 47-54.

2. B. Joiner and V. Adams, “Measurement and Simulation of Junction to Board Thermal Resistance and Its Application in Thermal Modeling,” Proceedings of SemiTherm, San Diego, 1999, pp. 212-220.

Table 9. Bus Operation Timings (continued)

Num	Characteristic	33 MHz		40 MHz		50 MHz		66 MHz		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
B1d	CLKOUT phase jitter peak-to-peak for OSCLK ≥ 15 MHz	—	4	—	4	—	4	—	4	ns
	CLKOUT phase jitter peak-to-peak for OSCLK < 15 MHz	—	5	—	5	—	5	—	5	ns
B2	CLKOUT pulse width low (MIN = 0.4 x B1, MAX = 0.6 x B1)	12.1	18.2	10.0	15.0	8.0	12.0	6.1	9.1	ns
B3	CLKOUT pulse width high (MIN = 0.4 x B1, MAX = 0.6 x B1)	12.1	18.2	10.0	15.0	8.0	12.0	6.1	9.1	ns
B4	CLKOUT rise time	—	4.00	—	4.00	—	4.00	—	4.00	ns
B5	CLKOUT fall time	—	4.00	—	4.00	—	4.00	—	4.00	ns
B7	CLKOUT to A(0:31), BADDR(28:30), RD/$\overline{\text{WR}}$, $\overline{\text{BURST}}$, D(0:31), DP(0:3) output hold (MIN = 0.25 x B1)	7.60	—	6.30	—	5.00	—	3.80	—	ns
B7a	CLKOUT to TSIZ(0:1), $\overline{\text{REG}}$, $\overline{\text{RSV}}$, AT(0:3), $\overline{\text{BDIP}}$, PTR output hold (MIN = 0.25 x B1)	7.60	—	6.30	—	5.00	—	3.80	—	ns
B7b	CLKOUT to $\overline{\text{BR}}$, $\overline{\text{BG}}$, FRZ, VFLS(0:1), VF(0:2), IWP(0:2), LWP(0:1), $\overline{\text{STS}}$ output hold (MIN = 0.25 x B1)	7.60	—	6.30	—	5.00	—	3.80	—	ns
B8	CLKOUT to A(0:31), BADDR(28:30) RD/$\overline{\text{WR}}$, $\overline{\text{BURST}}$, D(0:31), DP(0:3), valid (MAX = 0.25 x B1 + 6.3)	—	13.80	—	12.50	—	11.30	—	10.00	ns
B8a	CLKOUT to TSIZ(0:1), $\overline{\text{REG}}$, $\overline{\text{RSV}}$, AT(0:3), $\overline{\text{BDIP}}$, PTR valid (MAX = 0.25 x B1 + 6.3)	—	13.80	—	12.50	—	11.30	—	10.00	ns
B8b	CLKOUT to $\overline{\text{BR}}$, $\overline{\text{BG}}$, VFLS(0:1), VF(0:2), IWP(0:2), FRZ, LWP(0:1), $\overline{\text{STS}}$ valid [4] (MAX = 0.25 x B1 + 6.3)	—	13.80	—	12.50	—	11.30	—	10.00	ns
B9	CLKOUT to A(0:31), BADDR(28:30), RD/$\overline{\text{WR}}$, $\overline{\text{BURST}}$, D(0:31), DP(0:3), TSIZ(0:1), $\overline{\text{REG}}$, $\overline{\text{RSV}}$, AT(0:3), PTR High-Z (MAX = 0.25 x B1 + 6.3)	7.60	13.80	6.30	12.50	5.00	11.30	3.80	10.00	ns
B11	CLKOUT to $\overline{\text{TS}}$, $\overline{\text{BB}}$ assertion (MAX = 0.25 x B1 + 6.0)	7.60	13.60	6.30	12.30	5.00	11.00	3.80	9.80	ns
B11a	CLKOUT to $\overline{\text{TA}}$, $\overline{\text{BI}}$ assertion (when driven by the memory controller or PCMCIA interface) (MAX = 0.00 x B1 + 9.30 [1])	2.50	9.30	2.50	9.30	2.50	9.30	2.50	9.80	ns
B12	CLKOUT to $\overline{\text{TS}}$, $\overline{\text{BB}}$ negation (MAX = 0.25 x B1 + 4.8)	7.60	12.30	6.30	11.00	5.00	9.80	3.80	8.50	ns

Table 9. Bus Operation Timings (continued)

Num	Characteristic	33 MHz		40 MHz		50 MHz		66 MHz		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
B12a	CLKOUT to $\overline{TA}$, $\overline{BI}$ negation (when driven by the memory controller or PCMCIA interface) (MAX = 0.00 x B1 + 9.00)	2.50	9.00	2.50	9.00	2.50	9.00	2.50	9.00	ns
B13	CLKOUT to $\overline{TS}$, $\overline{BB}$ High-Z (MIN = 0.25 x B1)	7.60	21.60	6.30	20.30	5.00	19.00	3.80	14.00	ns
B13a	CLKOUT to $\overline{TA}$, $\overline{BI}$ High-Z (when driven by the memory controller or PCMCIA interface) (MIN = 0.00 x B1 + 2.5)	2.50	15.00	2.50	15.00	2.50	15.00	2.50	15.00	ns
B14	CLKOUT to $\overline{TEA}$ assertion (MAX = 0.00 x B1 + 9.00)	2.50	9.00	2.50	9.00	2.50	9.00	2.50	9.00	ns
B15	CLKOUT to $\overline{TEA}$ High-Z (MIN = 0.00 x B1 + 2.50)	2.50	15.00	2.50	15.00	2.50	15.00	2.50	15.00	ns
B16	$\overline{TA}$, $\overline{BI}$ valid to CLKOUT (setup time) (MIN = 0.00 x B1 + 6.00)	6.00	—	6.00	—	6.00	—	6.00	—	ns
B16a	$\overline{TEA}$, $\overline{KR}$, $\overline{RETRY}$, $\overline{CR}$ valid to CLKOUT (setup time) (MIN = 0.00 x B1 + 4.5)	4.50	—	4.50	—	4.50	—	4.50	—	ns
B16b	$\overline{BB}$, $\overline{BG}$, $\overline{BR}$, valid to CLKOUT (setup time) [2] (4 MIN = 0.00 x B1 + 0.00)	4.00	—	4.00	—	4.00	—	4.00	—	ns
B17	CLKOUT to $\overline{TA}$, $\overline{TEA}$, $\overline{BI}$, $\overline{BB}$, $\overline{BG}$, $\overline{BR}$ valid (hold time) (MIN = 0.00 x B1 + 1.00 [3])	1.00	—	1.00	—	1.00	—	2.00	—	ns
B17a	CLKOUT to $\overline{KR}$, $\overline{RETRY}$, $\overline{CR}$ valid (hold time) (MIN = 0.00 x B1 + 2.00)	2.00	—	2.00	—	2.00	—	2.00	—	ns
B18	D(0:31), DP(0:3) valid to CLKOUT rising edge (setup time) [4] (MIN = 0.00 x B1 + 6.00)	6.00	—	6.00	—	6.00	—	6.00	—	ns
B19	CLKOUT rising edge to D(0:31), DP(0:3) valid (hold time) [4] (MIN = 0.00 x B1 + 1.00 [5])	1.00	—	1.00	—	1.00	—	2.00	—	ns
B20	D(0:31), DP(0:3) valid to CLKOUT falling edge (setup time) [6](MIN = 0.00 x B1 + 4.00)	4.00	—	4.00	—	4.00	—	4.00	—	ns
B21	CLKOUT falling edge to D(0:31), DP(0:3) valid (hold Time) [6] (MIN = 0.00 x B1 + 2.00)	2.00	—	2.00	—	2.00	—	2.00	—	ns
B22	CLKOUT rising edge to $\overline{CS}$ asserted GPCM ACS = 00 (MAX = 0.25 x B1 + 6.3)	7.60	13.80	6.30	12.50	5.00	11.30	3.80	10.00	ns
B22a	CLKOUT falling edge to $\overline{CS}$ asserted GPCM ACS = 10, TRLX = 0 (MAX = 0.00 x B1 + 8.00)	—	8.00	—	8.00	—	8.00	—	8.00	ns

Figure 12 through Figure 15 show the timing for the external bus read controlled by various GPCM factors.

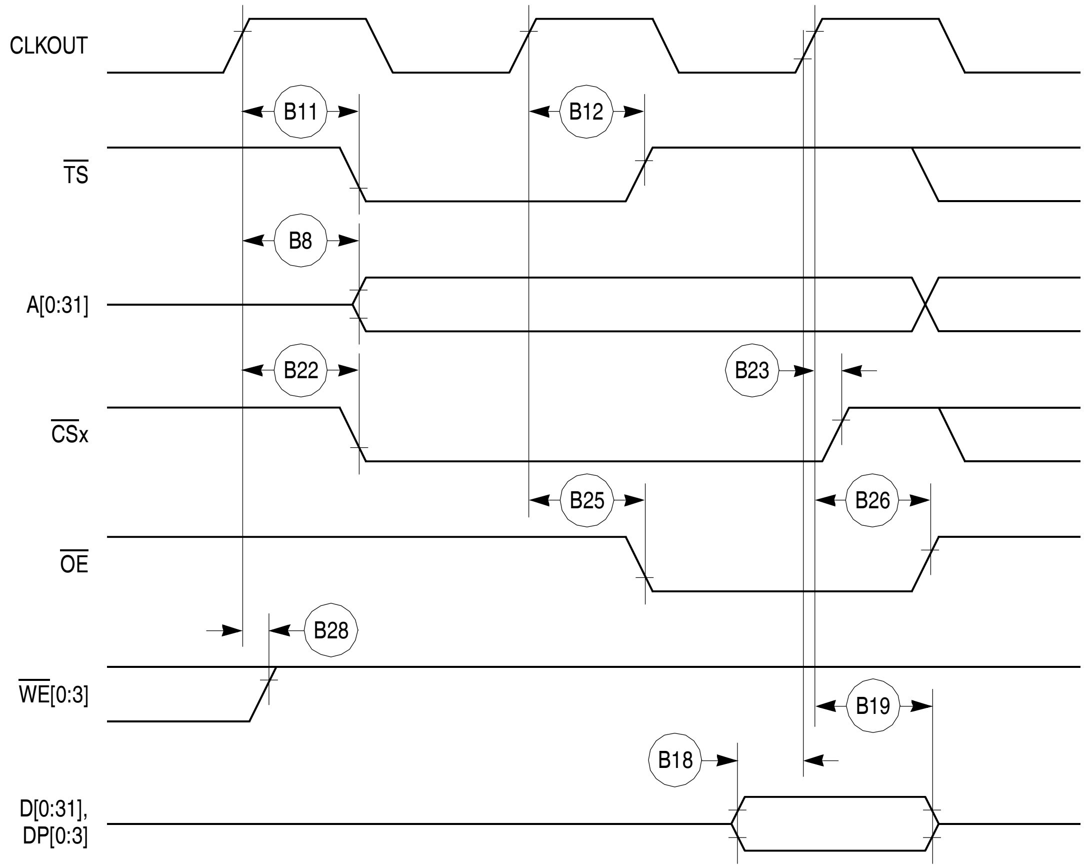


Figure 12. External Bus Read Timing (GPCM Controlled—ACS = 00)

Figure 25 shows the interrupt detection timing for the external level-sensitive lines.

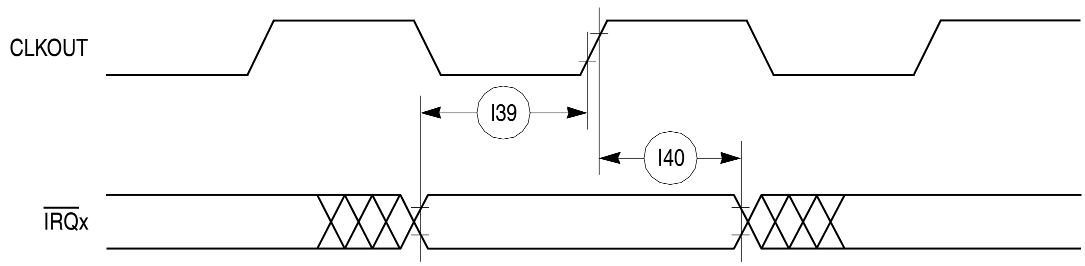


Figure 25. Interrupt Detection Timing for External Level Sensitive Lines

Figure 26 shows the interrupt detection timing for the external edge-sensitive lines.

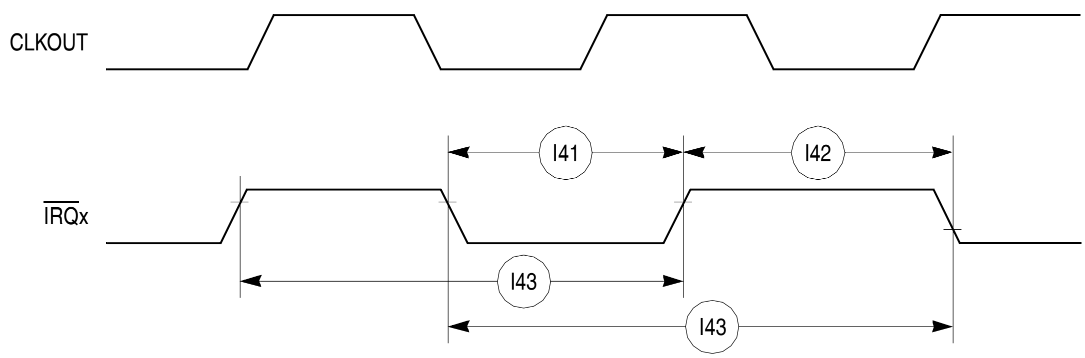


Figure 26. Interrupt Detection Timing for External Edge Sensitive Lines

Table 11 shows the PCMCIA timing for the MPC866/859.

Table 11. PCMCIA Timing

Num	Characteristic	33 MHz		40 MHz		50 MHz		66 MHz		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
P44	A(0:31), $\overline{\text{REG}}$ valid to PCMCIA Strobe asserted [1] (MIN = 0.75 x B1 – 2.00)	20.70	—	16.70	—	13.00	—	9.40	—	ns
P45	A(0:31), $\overline{\text{REG}}$ valid to ALE negation[1] (MIN = 1.00 x B1 – 2.00)	28.30	—	23.00	—	18.00	—	13.20	—	ns
P46	CLKOUT to $\overline{\text{REG}}$ valid (MAX = 0.25 x B1 + 8.00)	7.60	15.60	6.30	14.30	5.00	13.00	3.80	11.80	ns
P47	CLKOUT to $\overline{\text{REG}}$ invalid (MIN = 0.25 x B1 + 1.00)	8.60	—	7.30	—	6.00	—	4.80	—	ns
P48	CLKOUT to $\overline{\text{CE1}}$, $\overline{\text{CE2}}$ asserted (MAX = 0.25 x B1 + 8.00)	7.60	15.60	6.30	14.30	5.00	13.00	3.80	11.80	ns
P49	CLKOUT to $\overline{\text{CE1}}$, $\overline{\text{CE2}}$ negated (MAX = 0.25 x B1 + 8.00)	7.60	15.60	6.30	14.30	5.00	13.00	3.80	11.80	ns

Figure 28 shows the PCMCIA access cycle timing for the external bus write.

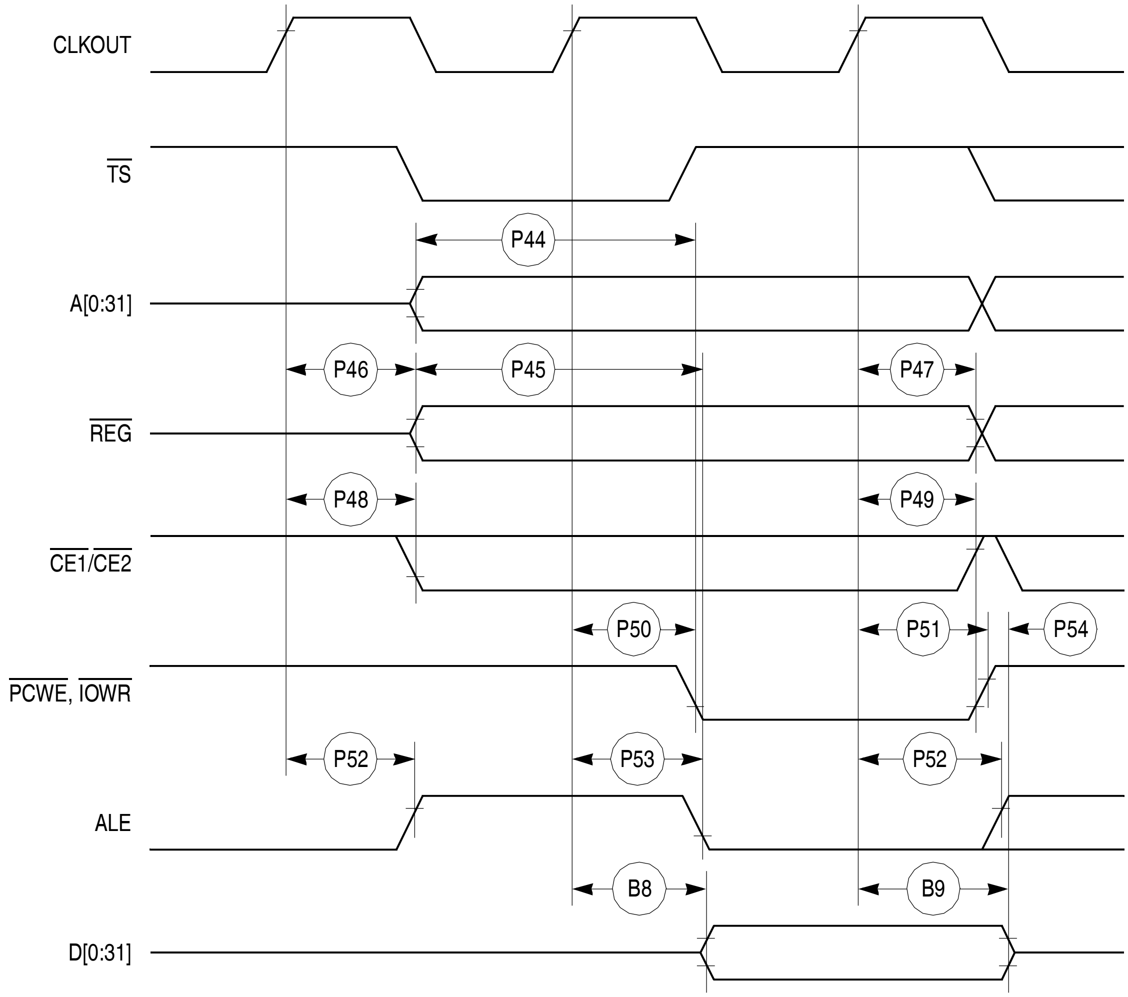


Figure 28. PCMCIA Access Cycles Timing External Bus Write

Figure 29 shows the PCMCIA $\overline{\text{WAIT}}$ signals detection timing.

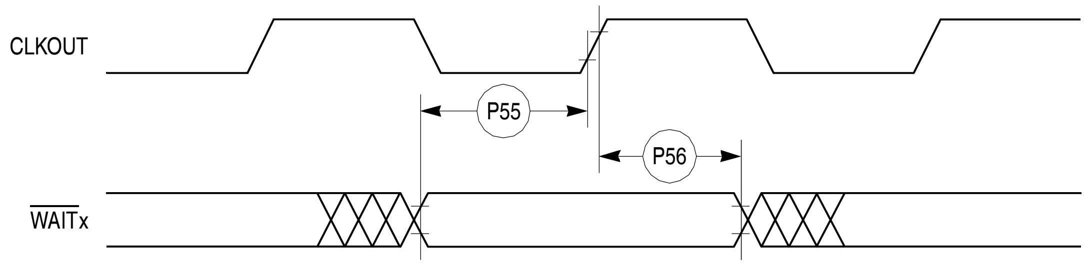


Figure 29. PCMCIA $\overline{\text{WAIT}}$ Signals Detection Timing

Figure 34 shows the reset timing for the data bus configuration.

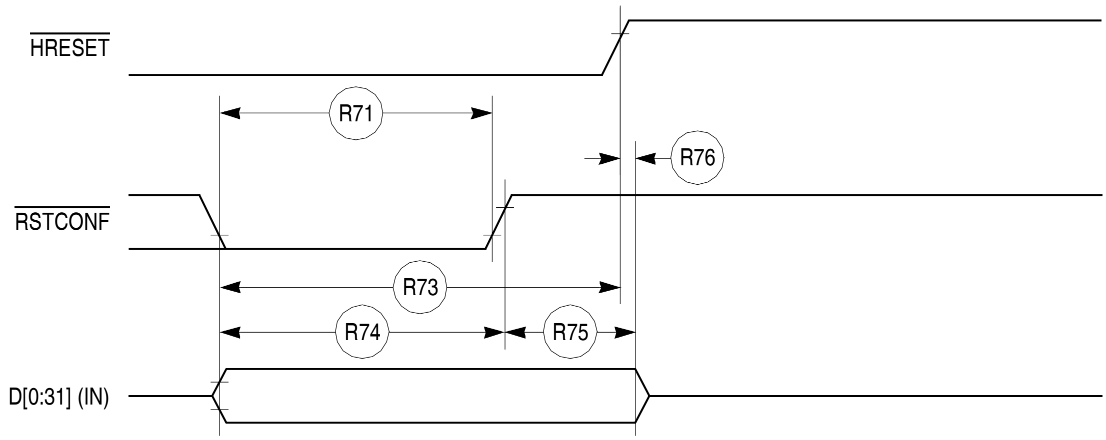


Figure 34. Reset Timing—Configuration from Data Bus

Figure 35 shows the reset timing for the data bus weak drive during configuration.

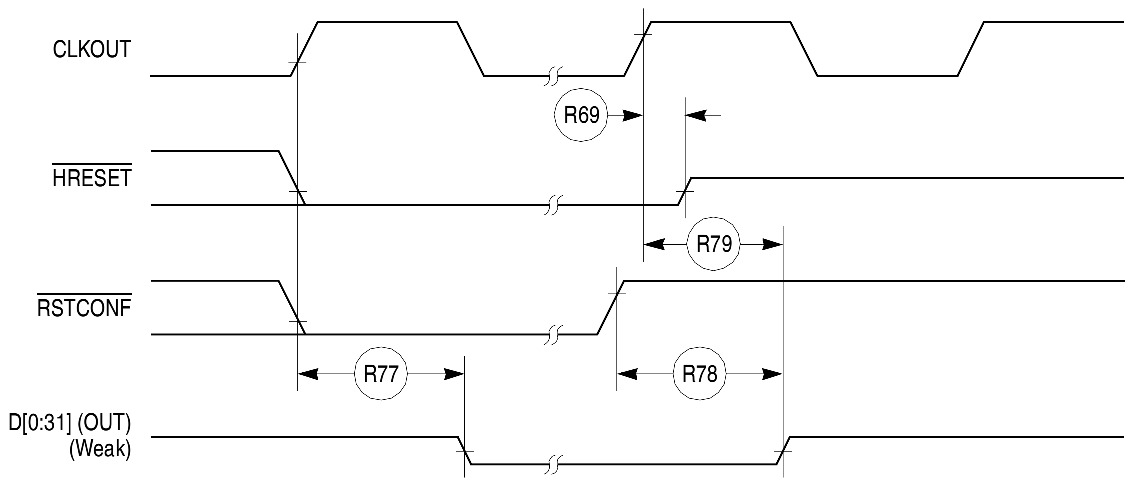


Figure 35. Reset Timing—Data Bus Weak Drive During Configuration

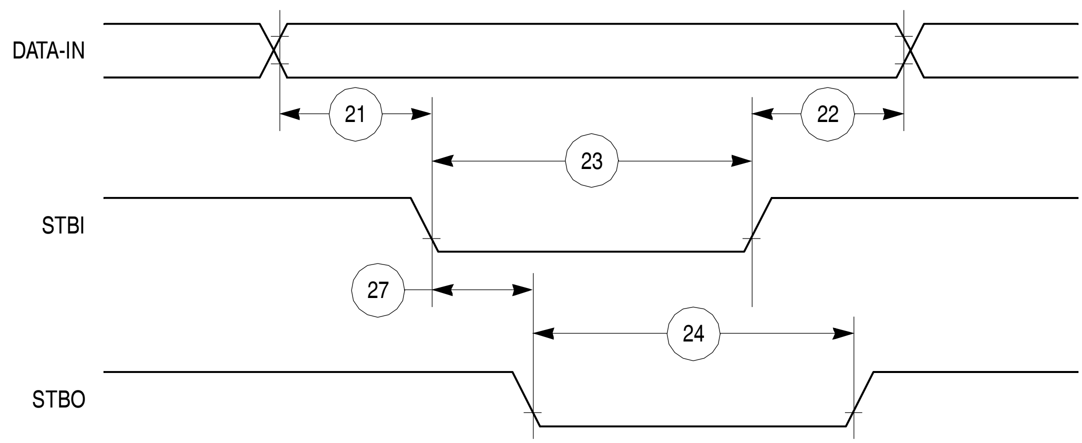


Figure 41. PIP Rx (Interlock Mode) Timing Diagram

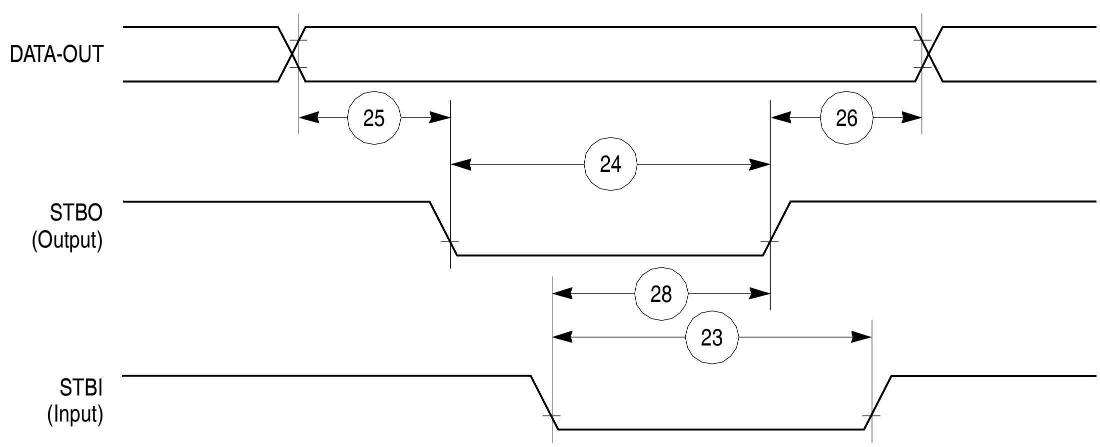


Figure 42. PIP Tx (Interlock Mode) Timing Diagram

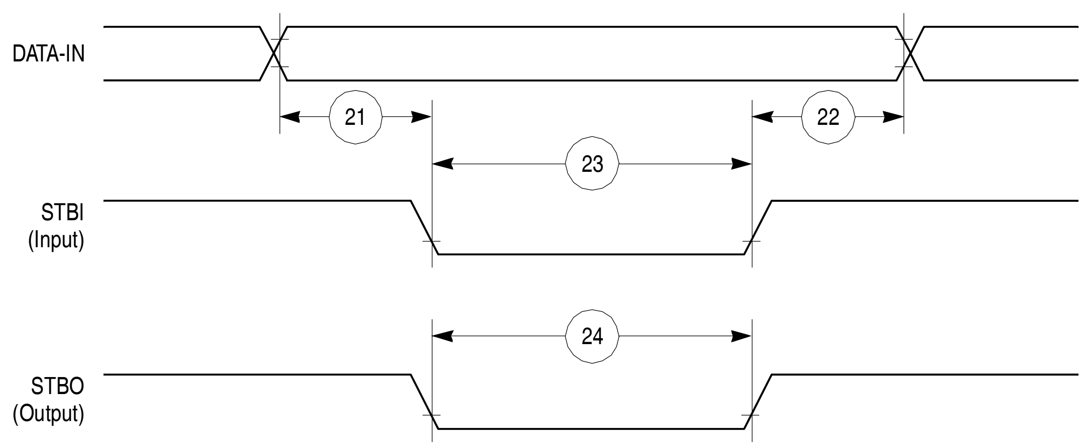


Figure 43. PIP Rx (Pulse Mode) Timing Diagram

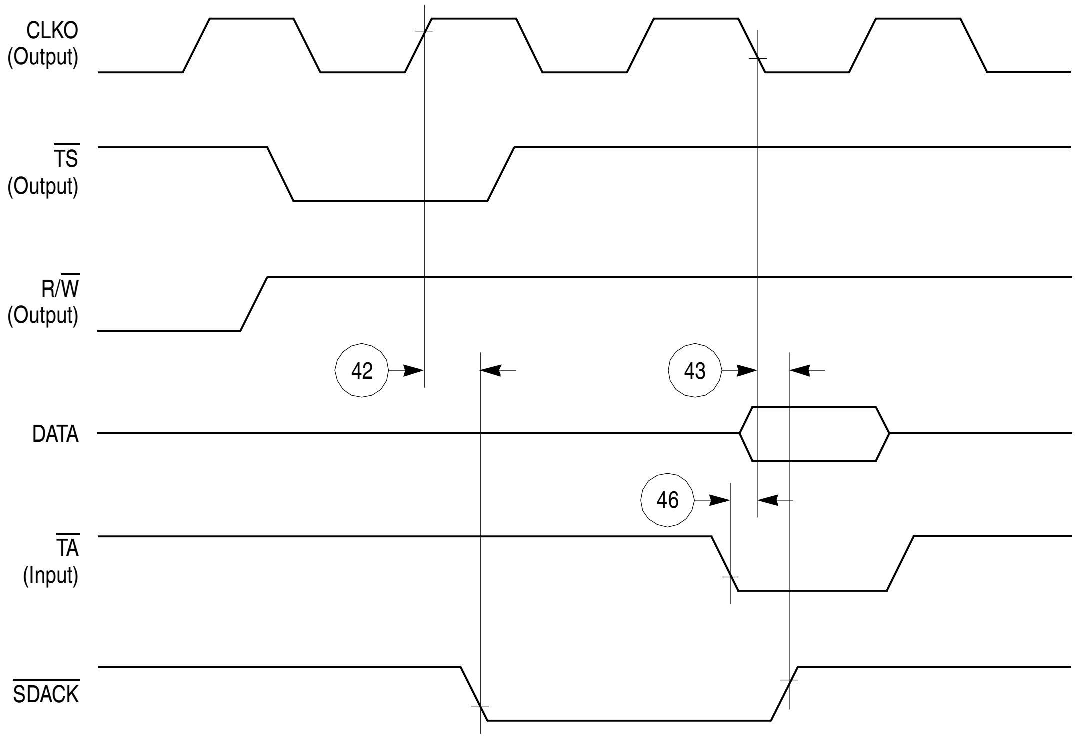


Figure 48. $\overline{\text{SDACK}}$ Timing Diagram—Peripheral Write, Externally-Generated $\overline{\text{TA}}$

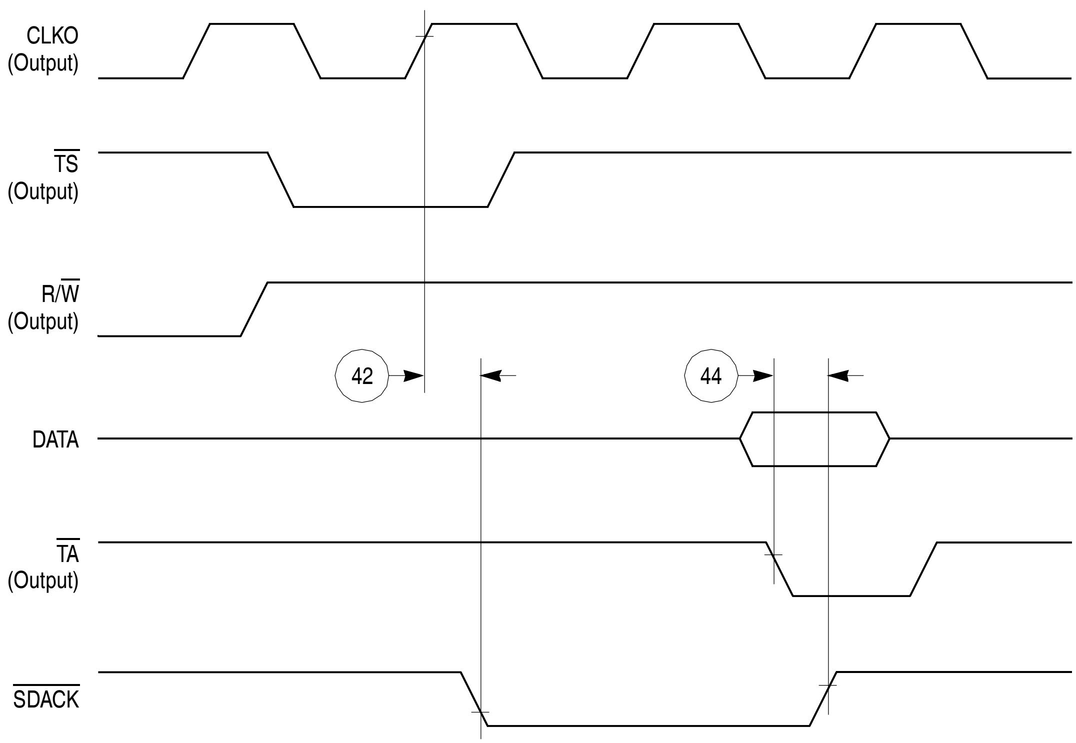


Figure 49. $\overline{\text{SDACK}}$ Timing Diagram—Peripheral Write, Internally-Generated $\overline{\text{TA}}$

Table 21. SI Timing (continued)

Num	Characteristic	All Frequencies		Unit
		Min	Max	
74	L1CLK edge to L1RSYNC, L1TSYNC, invalid (SYNC hold time)	35.00	—	ns
75	L1RSYNC, L1TSYNC rise/fall time	—	15.00	ns
76	L1RXD valid to L1CLK edge (L1RXD setup time)	17.00	—	ns
77	L1CLK edge to L1RXD invalid (L1RXD hold time)	13.00	—	ns
78	L1CLK edge to L1ST(1–4) valid [4]	10.00	45.00	ns
78A	L1SYNC valid to L1ST(1–4) valid	10.00	45.00	ns
79	L1CLK edge to L1ST(1–4) invalid	10.00	45.00	ns
80	L1CLK edge to L1TXD valid	10.00	55.00	ns
80A	L1TSYNC valid to L1TXD valid [4]	10.00	55.00	ns
81	L1CLK edge to L1TXD high impedance	0.00	42.00	ns
82	L1RCLK, L1TCLK frequency (DSC =1)	—	16.00 or SYNCCLK/2	MHz
83	L1RCLK, L1TCLK width low (DSC =1)	P + 10	—	ns
83a	L1RCLK, L1TCLK width high (DSC = 1)[3]	P + 10	—	ns
84	L1CLK edge to L1CLKO valid (DSC = 1)	—	30.00	ns
85	$\overline{\text{L1RQ}}$ valid before falling edge of L1TSYNC[4]	1.00	—	L1TCLK
86	L1GR setup time[2]	42.00	—	ns
87	L1GR hold time	42.00	—	ns
88	L1CLK edge to L1SYNC valid (FSD = 00) CNT = 0000, BYT = 0, DSC = 0)	—	0.00	ns

1 The ratio SyncCLK/L1RCLK must be greater than 2.5/1.
2 These specs are valid for IDL mode only.
3 Where P = 1/CLKOUT. Thus, for a 25-MHz CLKO1 rate, P = 40 ns.
4 These strobes and TxD on the first bit of the frame become valid after L1CLK edge or L1SYNC, whichever is later.

12.10 SPI Master AC Electrical Specifications

Table 26 shows the SPI master timings as shown in Figure 67 and Figure 68.

Table 26. SPI Master Timing

Num	Characteristic	All Frequencies		Unit
		Min	Max	
160	MASTER cycle time	4	1024	t_{cyc}
161	MASTER clock (SCK) high or low time	2	512	t_{cyc}
162	MASTER data setup time (inputs)	15	—	ns
163	Master data hold time (inputs)	0	—	ns
164	Master data valid (after SCK edge)	—	10	ns
165	Master data hold time (outputs)	0	—	ns
166	Rise time output	—	15	ns
167	Fall time output	—	15	ns

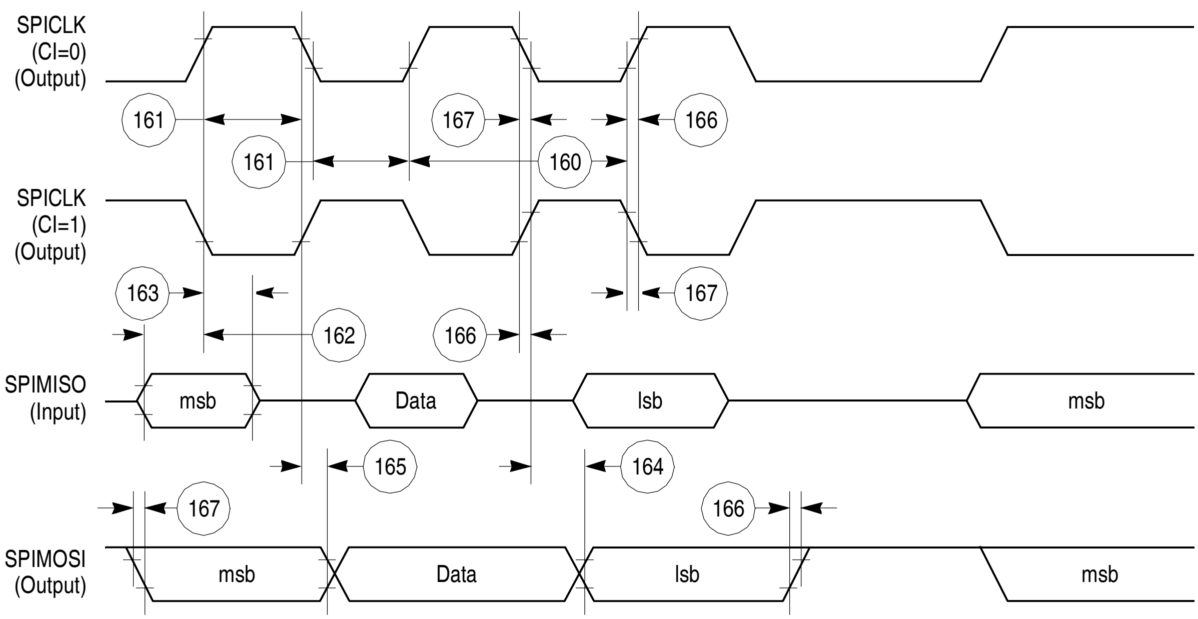


Figure 67. SPI Master (CP = 0) Timing Diagram

Table 38. MPC866/859 Package/Frequency Orderable (continued)

Plastic ball grid array (VR suffix) Lead free	0° to 95°C	50	MPC859DSLVR50A
		66	MPC859DSLVR66A
		100	MPC859PVR100A MPC859TVR100A MPC866PVR100A MPC866TVR100A
		133	MPC859PVR133A MPC859TVR133A MPC866PVR133A MPC866TVR133A
Plastic ball grid array (CVR suffix) Lead free	–40° to 100°C	50	MPC859DSLCVR50A
		66	MPC859DSLCVR66A
		100	MPC859PCVR100A MPC859TCVR100A MPC866PCVR100A MPC866TCVR100A

Table 39. Pin Assignments (continued)

Name	Pin Number	Type
UPWAITB GPL_B4	B1	Bidirectional
GPL_A5	D3	Output
PORESET	R2	Input
RSTCONF	P3	Input
HRESET	N4	Open-drain
SRESET	P2	Open-drain
XTAL	P1	Analog Output
EXTAL	N1	Analog Input (3.3V only)
CLKOUT	W3	Output
EXTCLK	N2	Input (3.3V only)
TEXP	N3	Output
ALE_A MII-TXD1	K2	Output
CE1_A MII-TXD2	B3	Output
CE2_A MII-TXD3	A3	Output
WAIT_A SOC_Split[2]	R3	Input
WAIT_B	R4	Input
IP_A0 UTPB_Split0[2] MII-RXD3	T5	Input
IP_A1 UTPB_Split1[2] MII-RXD2	T4	Input
IP_A2 IOIS16_A UTPB_Split2[2] MII-RXD1	U3	Input
IP_A3 UTPB_Split3[2] MII-RXD0	W2	Input
IP_A4 UTPB_Split4[2] MII-RXCLK	U4	Input

Table 39. Pin Assignments (continued)

Name	Pin Number	Type
OP3 MODCK2 DSDO	M4	Bidirectional
BADDR30 $\overline{\text{REG}}$	K4	Output
BADDR[28:29]	M3, M2	Output
$\overline{\text{AS}}$	L3	Input
PA15 RXD1 RXD4	C18	Bidirectional
PA14 TXD1 TXD4	D17	Bidirectional (Optional: Open-drain)
PA13 RXD2	E17	Bidirectional
PA12 TXD2	F17	Bidirectional (Optional: Open-drain)
PA11 L1TXDB RXD3	G16	Bidirectional (Optional: Open-drain)
PA10 L1RXDB TXD3	J17	Bidirectional (Optional: Open-drain)
PA9 L1TXDA RXD4	K18	Bidirectional (Optional: Open-drain)
PA8 L1RXDA TXD4	L17	Bidirectional (Optional: Open-drain)
PA7 CLK1 L1RCLKA BRGO1 TIN1	M19	Bidirectional
PA6 CLK2 $\overline{\text{TOUT1}}$	M17	Bidirectional

Table 39. Pin Assignments (continued)

Name	Pin Number	Type
PC7 $\overline{\text{CTS3}}$ L1TSYNCB $\overline{\text{SDACK2}}$	M16	Bidirectional
PC6 $\overline{\text{CD3}}$ L1RSYNCB	R19	Bidirectional
PC5 $\overline{\text{CTS4}}$ L1TSYNCA SDACK1	T18	Bidirectional
PC4 $\overline{\text{CD4}}$ L1RSYNCA	T17	Bidirectional
PD15 L1TSYNCA MII-RXD3 UTPB0	U17	Bidirectional
PD14 L1RSYNCA MII-RXD2 UTPB1	V19	Bidirectional
PD13 L1TSYNCB MII-RXD1 UTPB2	V18	Bidirectional
PD12 L1RSYNCB MII-MDC UTPB3	R16	Bidirectional
PD11 RXD3 MII-TXERR $\overline{\text{RXENB}}$	T16	Bidirectional
PD10 TXD3 MII-RXD0 $\overline{\text{TXENB}}$	W18	Bidirectional

Table 39. Pin Assignments (continued)

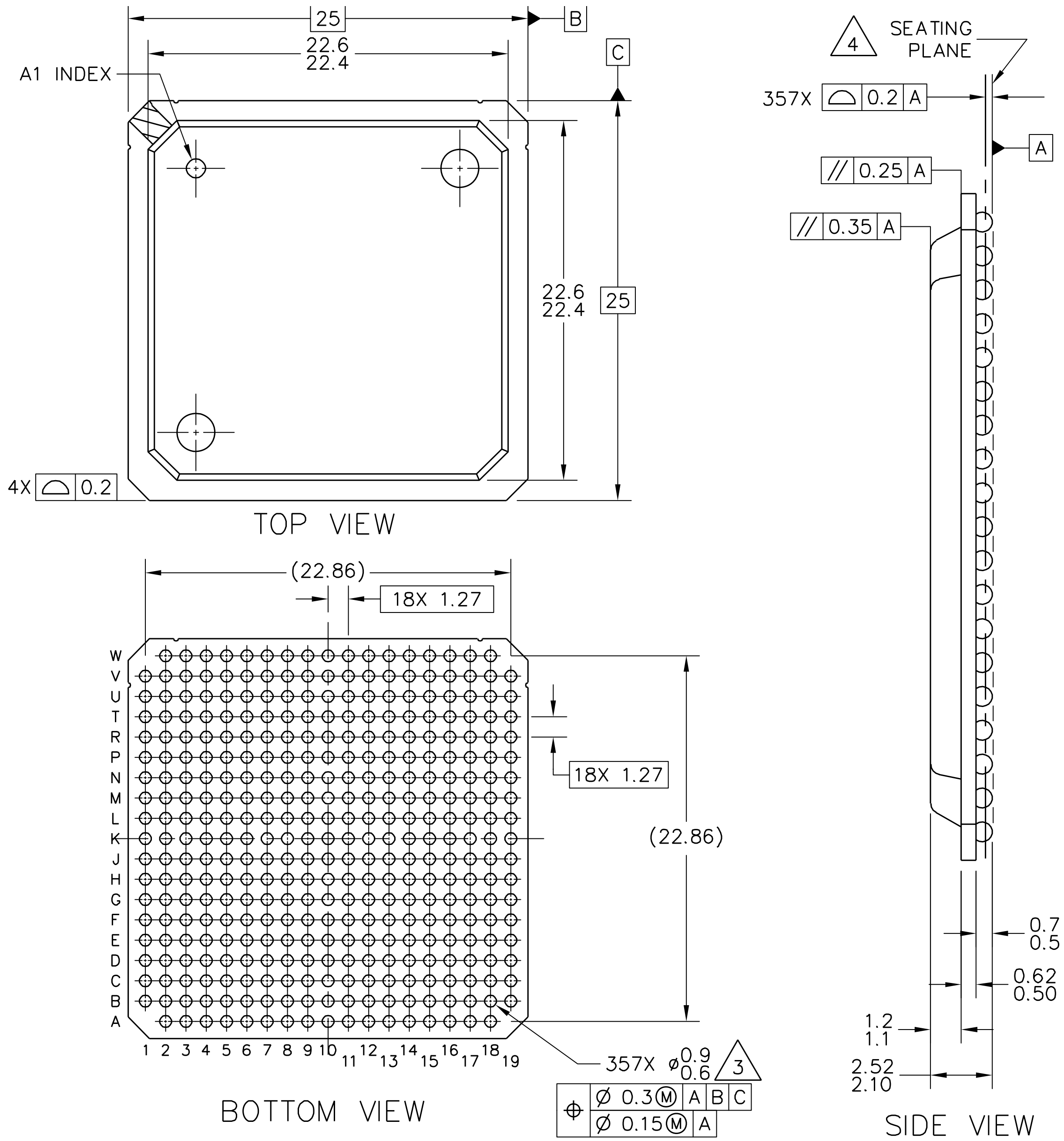
Name	Pin Number	Type
MII_COL	H4	Input
VSSSYN1	V1	PLL analog VDD and GND
VSSSYN	U1	Power
VDDSYN	T1	Power
GND	F6, F7, F8, F9, F10, F11, F12, F13, F14, G6, G7, G8, G9, G10, G11, G12, G13, G14, H6, H7, H8, H9, H10, H11, H12, H13, H14, J6, J7, J8, J9, J10, J11, J12, J13, J14, K6, K7, K8, K9, K10, K11, K12, K13, K14, L6, L7, L8, L9, L10, L11, L12, L13, L14, M6, M7, M8, M9, M10, M11, M12, M13, M14, N6, N7, N8, N9, N10, N11, N12, N13, N14, P6, P7, P8, P9, P10, P11, P12, P13, P14	Power
VDDL	A8, M1, W8, H19, F4, F16, P4, P16, R1	Power
VDDH	E5, E6, E7, E8, E9, E10, E11, E12, E13, E14, E15, F5, F15, G5, G15, H5, H15, J5, J15, K5, K15, L5, L15, M5, M15, N5, N15, P5, P15, R5, R6, R7, R8, R9, R10, R11, R12, R13, R14, R15, T14	Power
N/C	D6, D13, D14, U2, V2, T2	No-connect

[1] Classic SAR mode only

[2] ESAR mode only

15.2 Mechanical Dimensions of the PBGA Package

For more information on the printed-circuit board layout of the PBGA package, including thermal via design and suggested pad layout, please refer to *Plastic Ball Grid Array Application Note* (order number: AN1231/D) available from your local Freescale sales office. Figure 79 shows the mechanical dimensions of the PBGA package.



Note: Solder sphere composition for MPC866XZP, MPC859PZP, MPC859DSLZP, and MPC859TZP is 62%Sn 36%Pb 2%Ag

Figure 79. Mechanical Dimensions and Bottom Surface Nomenclature of the PBGA Package